



S1141 170

(UL ANSI:FR-4)UV Blocking/ High Tg

特点

- 高Tg170℃ (DSC)。
- UV Blocking/AOI兼容。
- 优良的PCB加工性能。

应用领域

计算机及外围设备、通讯设备、仪器仪表、办公自动设备等。

FEATURES

- High Tg170℃ (DSC) .
- UV Blocking/AOI Compatible.
- Good PCB processability.

APPLICATIONS

Computer, communication equipment instrumentation, OA equipment, and etc.

GENERAL PROPERTIES

Test Item	Treatment Condition	Unit	Property Data	
			SPEC	Typical Value
Tg	DSC	℃	≥ 170	175
Flammability	C-48/23/50	Rating	V-0	V-0
	E-24/125			
Volume Resistivity	After moisture resistance	MΩ-cm	≥ 10 ⁶	5.2×10 ⁸
	E-24/125		≥ 10 ³	5.3×10 ⁶
Surface Resistivity	After moisture resistance	MΩ	≥ 10 ⁴	5.4×10 ⁷
	E-24/125		≥ 10 ³	5.1×10 ⁶
Arc Resistance	D-48/50+D-0.5/23	S	≥60	115
Dielectric Breakdown	D-48/50+D-0.5/23	KV	≥ 40	55
Dielectric Constant (1MHz)	C-24/23/50	-	≤ 5.4	4.5
Dissipation Factor (1MHz)	C-24/23/50	-	≤ 0.035	0.016
Thermal Stress	288℃, solder dip	-	> 10s	60s
			No delamination	No delamination
Peel Strength	288℃, 10s	N/mm	≥ 1.05	1.7
	1oz Cu. Foil 125℃		≥ 0.70	1.5
Flexural Strength	A	MPa	≥ 415	600
			≥ 345	500
Water Absorption	D-24/23	%	≤ 0.80	0.15
CTE Z-axis	Before Tg	TMA	μ m/m℃	55
	After Tg	TMA	μ m/m℃	290
	50~260℃	TMA	%	4.0
Td	10℃/min, N ₂ , 5% Wt Loss	℃	-	300
T260	TMA	min	-	8
T288	TMA	min	-	-
CTI	IEC60112 Method	V	PLC 3(175V--249V)	PLC 3

Remarks: 1.Specification sheet:IPC-4101/24, is for your reference only.
 2.All the typical value is based on the 1.6mm specimen,while the Tg is for specimen ≥0.50mm.
 3.All the typical value listed above is for your reference only, please turn to Shengyi Sci.Tech.Co., Ltd . for detailed information, and all rights from this data sheet are reserved by Shengyi Sci.Tech.Co., Ltd .

Explanations: C = Humidity conditioning; D = Immersion conditioning in distilled water; E = Temperature conditioning.

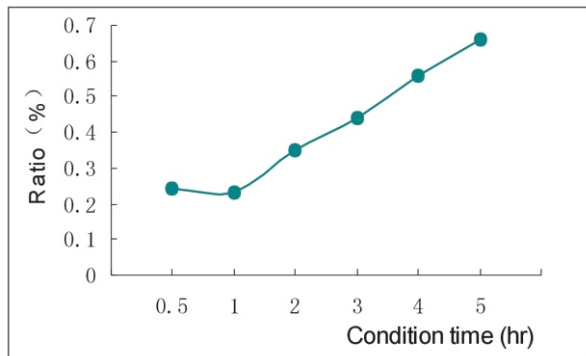
The figures following the letter symbols indicate with the first digit the duration of the preconditioning in hours, with the second digit the preconditioning temperature in ℃ and with the third digit the relative humidity.



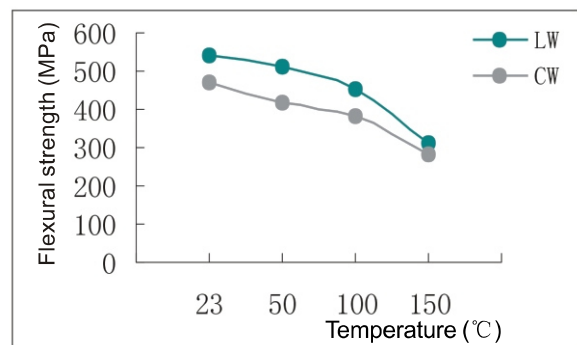
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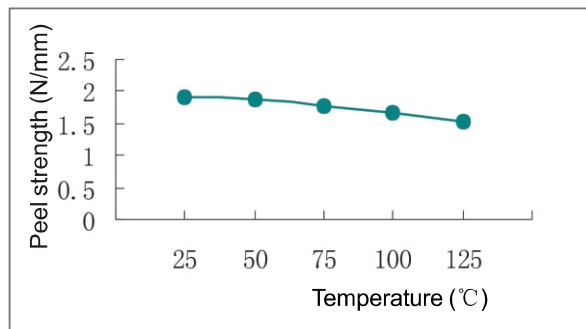
Water absorption at pressure cooker



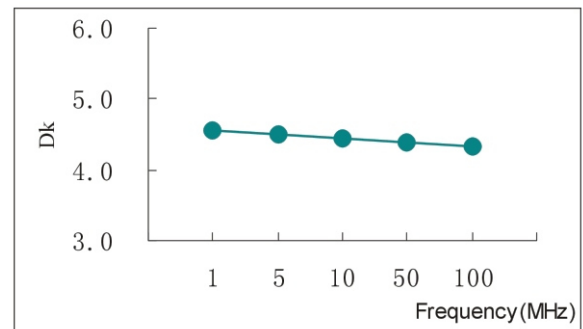
Flexural strength



Peel strength



Dielectric constant



PURCHASING INFORMATION

Thickness	Copper foil	Standard Size
0.05mm to 3.2mm	12 μ m to 105 μ m	1,020×1,220mm (40" × 48") 915×1,220mm (36" × 48") 1,070×1,220mm (42" × 48")

❖ Other sheet size and thickness could be available upon request.



S0401 170 PREPREG

(UL ANSI:FR-4) Bonding Prepreg For S1141 170

特点

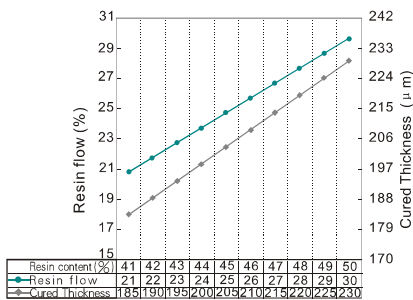
- Tg170℃ (DSC)。
- UV Blocking/AOI兼容。
- 优良的粘结性能，作业窗口宽。

FEATURES

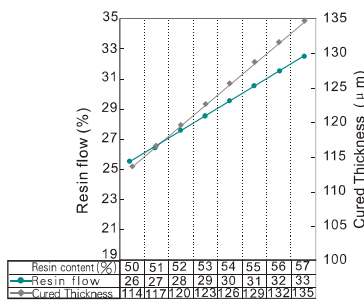
- Tg170℃ (DSC) .
- UV Blocking/AOI Compatible.
- Excellent bonding strength ,wide operating window.

PREPREG PARAMETERS

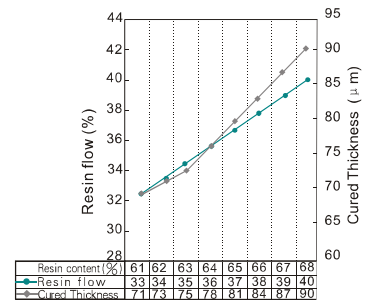
7628 TYPE PREPREG



2116 TYPE PREPREG



1080 TYPE PREPREG



Designation	Glass fabric type	Performance	Gel time (sec)	Resin Content (%)	Resin flow (%)	Cured Thickness (μm)	Standard Size (roll type)
S0401170	106	High Tg (Tg 170℃)	140±20	71±3	37±5	50±10	1,260mm×114.3m (125yards)
	106LD			71±3	37±5	50±10	
	1078LD			64±3	36±5	78±10	
	1080			X±3	X±5	X±10	
	1086LD			61±3	33±5	78±10	
	2112			57±3	30±5	90±15	
	2113			56±3	26±5	100±15	
	2313			55±3	26±5	100±15	
	3313			55±3	26±5	100±15	
	2116			X±3	X±5	X±15	
	2165			52±3	26±5	140±15	
	1500			45±3	22±5	160±15	
7628	X±3	X±5	X±20				

Type, Resin Content and Size Could be Available Upon Request

Prepreg Test Method

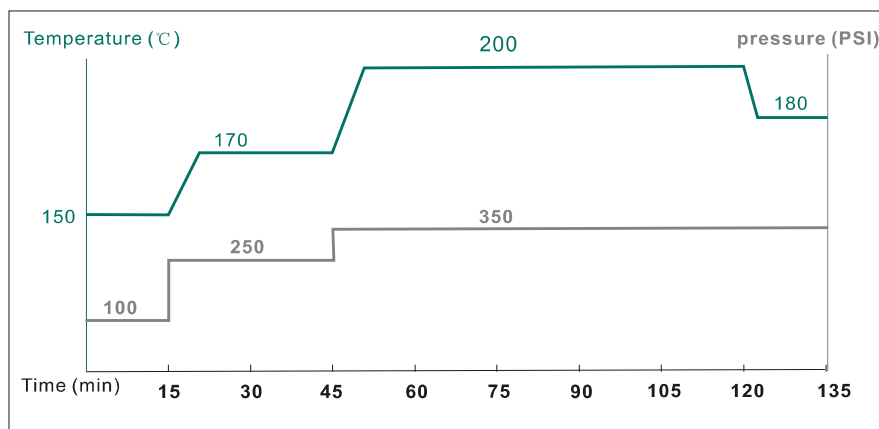
- Resin Content, Resin Flow, Gel Time: IPC-TM-650



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HOT PRESSING CYCLE



Heat-up rate: 1.5~2.5°C/min(80~140°C)

Curing time: >45min(180~190°C)

The hot pressing parameters is for your reference only, please turn to Shengyi Sci.Tech.Co., Ltd for detailed information.

PREPREG STORAGE

STORAGE CONDITION

- Three months when stored at <23°C and <50% RH .
- Six months when stored at <5°C . Normalize in room temperature for at least 4h before using.
- Beware of moisture, always keep wrapped in damp-proof material. Were kept in normal condition, prepreg might absorb moisture and its bonding strength would be weakened.
- Avoid UV-rays and strong light.